

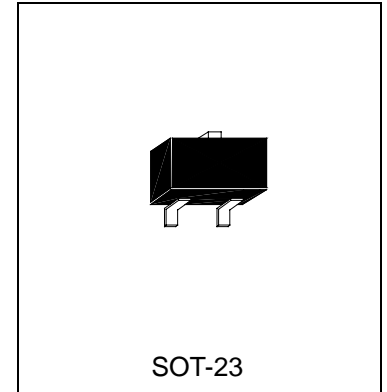


HMBTA06

NPN SILICON TRANSISTOR

Description

Amplifier Transistor



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 225 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCB0 Collector to Base Voltage 80 V
 VCEO Collector to Emitter Voltage..... 80 V
 VEBO Emitter to Base Voltage..... 4 V
 IC Collector Current..... 500 mA

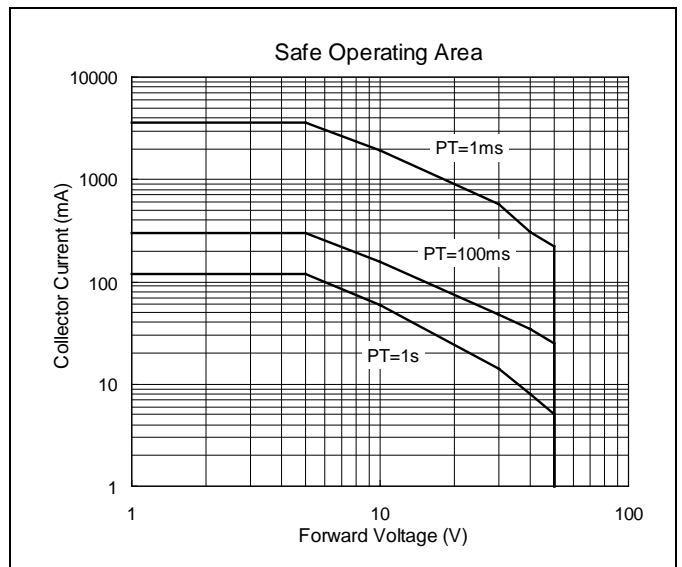
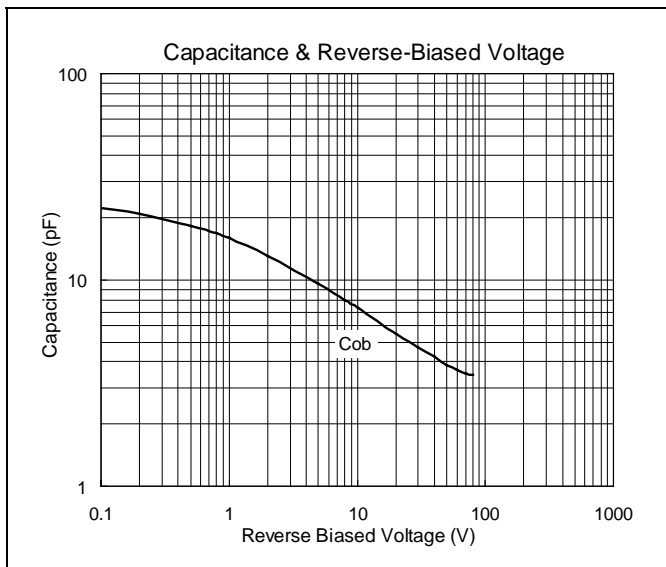
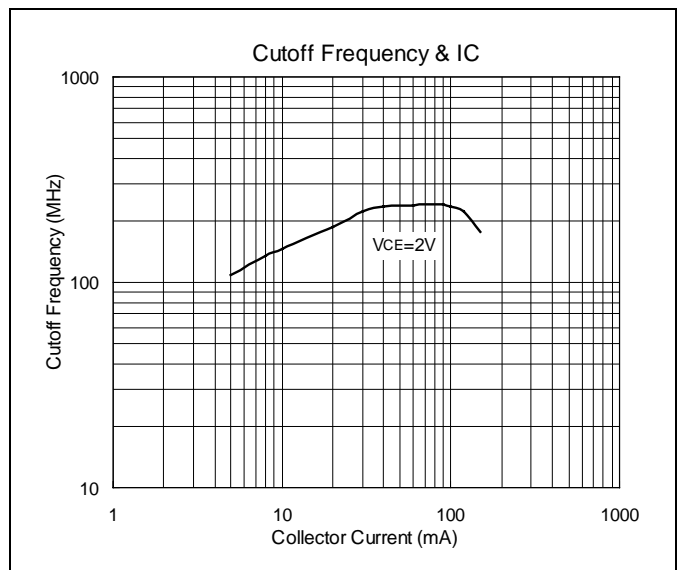
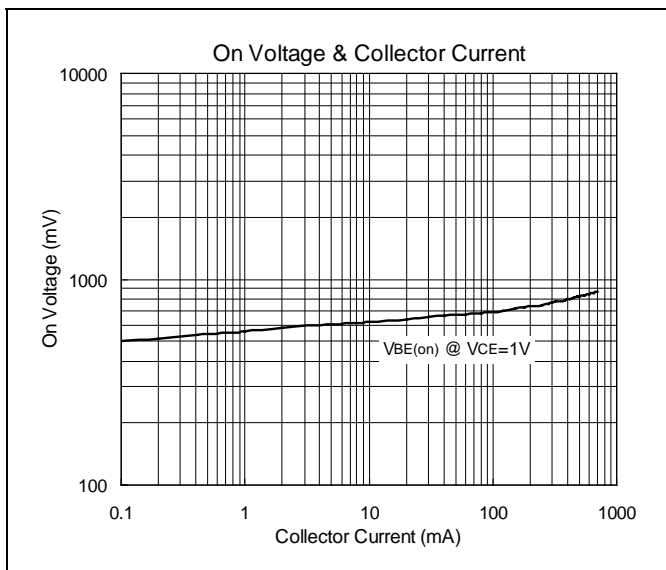
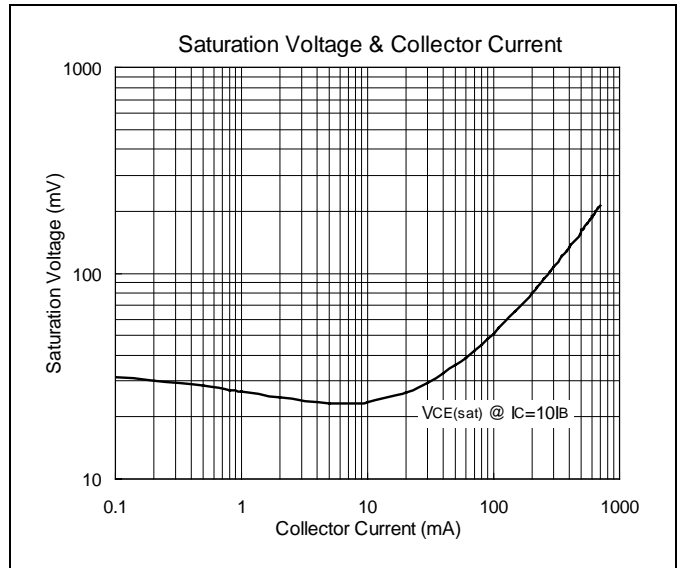
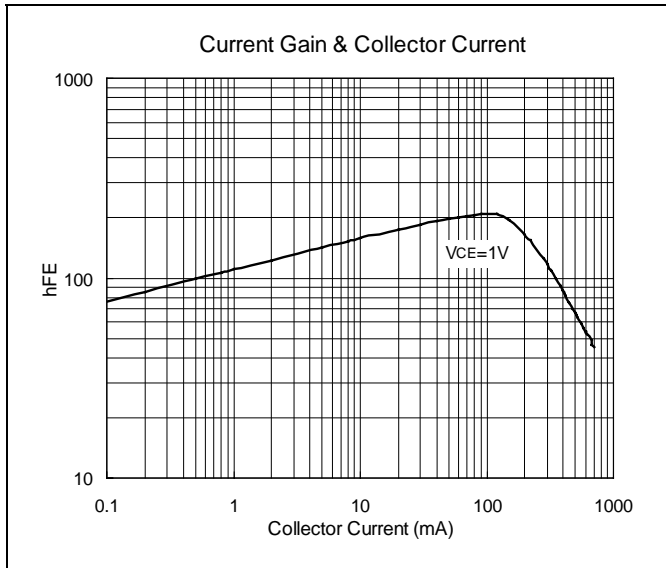
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	80	-	-	V	IC=100uA
BVCEO	80	-	-	V	IC=1mA
BVEBO	4	-	-	V	IE=100uA
ICBO	-	-	100	nA	VCB=80V
ICEO	-	-	100	nA	VCE=60V
*VCE(sat)	-	-	0.25	V	IC=100mA, IB=10mA
VBE(on)	-	-	1.2	V	IC=100mA, VCE=1V
*hFE1	50	-	-		IC=10mA, VCE=1V
*hFE2	50	-	-		IC=100mA, VCE=1V
fT	100	-	-	MHz	IC=10mA, VCE=2V, f=100MHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

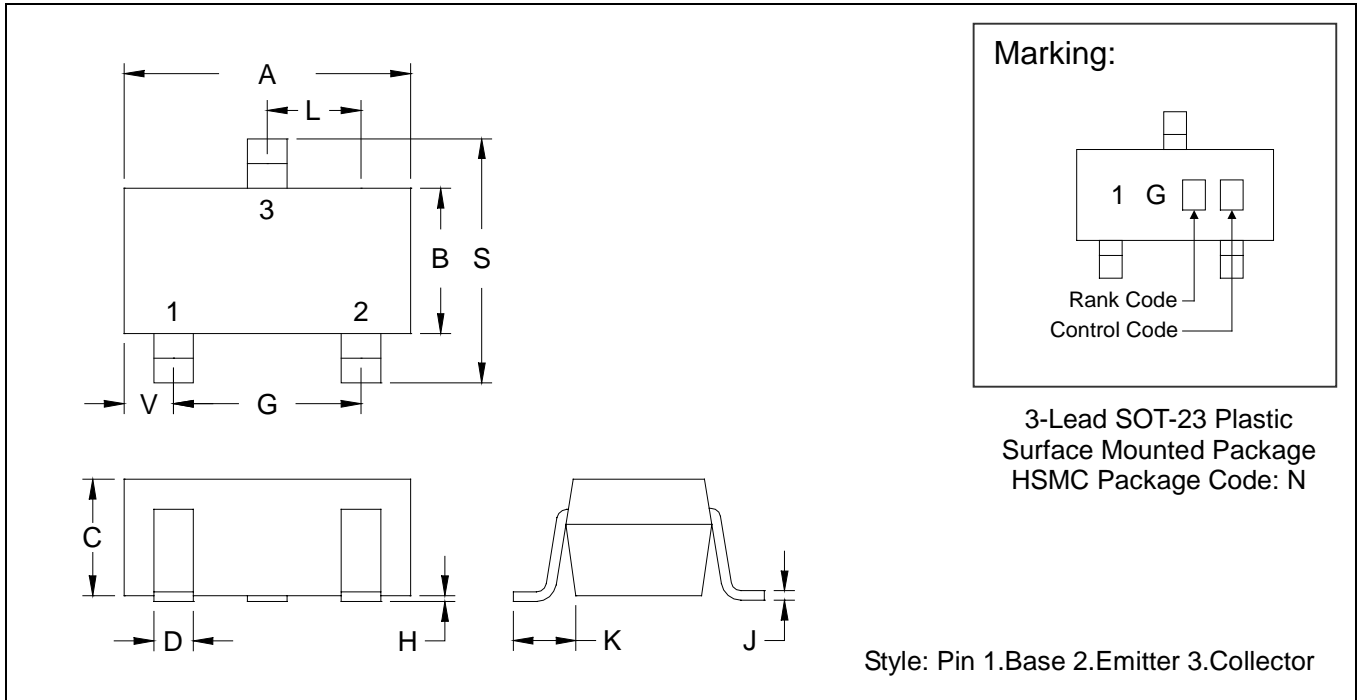


Characteristics Curve





SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

- Notes: 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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